

IN THE CLAIMS:

1. (Currently Amended) A flip-chip packaging method, ~~method wherein in for attaching flip-chip packaging a~~ semiconductor element ~~on to~~ a circuit board ~~by using with~~ conductive resin, said element having protruding electrodes ~~formed thereon~~, the method comprising:

printing an electrode material containing photopolymerizable materials on a semiconductor element package region on said circuit board such that a film is formed with a prescribed thickness, and ~~forming~~ allowing said electrode material film to remain only on prescribed electrode areas, said remaining electrode material film, after having been exposed and developed, resulting in remaining areas of said electrode material film whose thickness in cross section is trapezoidal and widens in an outward direction from an interface of said remaining areas with the circuit board;

baking said trapezoidal electrode material remaining areas to form concave circuit electrodes ~~by baking said electrode material film after performing exposure and development of said electrode material film to allow said electrode material film to remain only on prescribed electrode regions, thereby forming concave circuit electrodes having~~

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edges warped in a direction ~~of going apart~~ away from the circuit board surface; and

bringing said protruding electrodes formed on said semiconductor element into abutment with concave faces of said concave circuit electrodes, and connecting said protruding electrodes and said circuit electrodes with each other via the conductive resin.

2. (Currently Amended) The flip-chip packaging method according to claim 1, wherein said electrode material film ~~is formed to have~~has a dry film thickness of 10 to 20 micrometers.

3. (Cancelled)

4. (Previously Presented) The flip-chip packaging method according to claim 1, wherein said circuit electrode is arc-shaped in cross section.

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5. (Currently Amended) A flip-chip package in which comprising:

a semiconductor element having protruding electrodes formed thereon ~~is packaged or~~ attached to a circuit board by ~~using a~~ conductive resin, wherein

said circuit board ~~includes~~ comprises concave circuit electrodes each having edges warped in a direction of ~~going apart~~ away from the circuit board surface, and

said semiconductor element is ~~disposed~~ located such that ends of said protruding electrodes thereof ~~come in abutment with~~ abut concave surfaces of said concave circuit electrodes, and

said protruding electrodes and said circuit electrodes are connected to each other via the conductive resin.

6. (Currently Amended) A circuit board for flip-chip packaging a semiconductor element thereto via a ~~by using~~ conductive resin, said element having protruding ~~electrodes~~ formed thereon, the circuit board comprising concave circuit electrodes each having edges warped in a direction of ~~going apart~~ away from the circuit board surface.